To the limits. And beyond.

Breaking New Ground since 1986
Since its early beginnings in 1986, Datacon has been breaking new ground in the IC manufacturing and packaging industry. Datacon's main area of expertise is the development and production of high-precision assembly equipment for the microchip industry. Leading microelectronics companies worldwide, such as Bosch, Fairchild, Siemens, Philips, Infineon, ST Micro, Skyworks and Asian subcontractors like Amkor, ASE and STATSChipPAC are among Datacon's customers.

Using a highly adaptable platform concept with modular systems, Datacon's product range offers a large degree of flexibility and modularity for the IC manufacturing industry. Datacon is one of the leading and most innovative providers of assembly equipment for the semiconductor industry and is ahead of the field when it comes to new technologies such as flip chip and RFID (non-contact data transmission). Offering dynamic, flexible concept strategies and latest technologies, Datacon is known in the die bonder market as a solution supplier and an essential research partner for the semiconductor industry worldwide.

Serving the Semiconductor Industry
Datacon has been part of the Dutch Besi group (BE Semiconductor Industries N.V.) since early 2005. Besi and its subsidiaries form a leading group of manufacturers of semiconductor die sorting, flip chip and multichip die bonding, wire bonding, packaging and plating equipment, for both array connect and leadframe assembly processes. Our technologically advanced equipment and integrated systems are used principally to produce semiconductor assemblies or "packages", which provide the electronic interface and physical connection between the chip and other electronic components and protect the chip from the external environment. Our innovative systems offer customers high productivity and improved yields from defect-free devices at a low total-cost-of-ownership.

GLOBAL HEADQUARTERS

Besi
BE Semiconductor
Industries N.V.
Ratio 6
6921 RW Duiven
The Netherlands
Tel. +31 26 319 45 00
Fax +31 26 319 45 50

YOUR GLOBAL NETWORK

South East Asia
Esec (Singapore) Pte. Ltd.
1, Science Park Road
Singapore Science Park 2
#03-10, Capricorn Building
Singapore 117528
Tel. + 65 6303 7000
Fax + 65 6873 1133

Meco Equipment Engineers
(Far East) Pte. Ltd.
40, Jalan Pemimpin #04-06A
Tat Ann Building
Singapore 577185
Tel. +65 6255 2722
Fax +65 6255 6766

Besi APac Sdn. Bhd.
3 Jalan 26/7
Section 26
40000 Shah Alam
Selangor Darul Ehsan
Malaysia
Tel. +603 5191 1719
Fax +603 5192 9416

China
Esec (Shanghai)
Trading Co. Ltd.
East 2/F, No. 32 Bldg
No. 76 Fu Te Dong San Road
Waigaoqiao Free Trade Zone
Shanghai 200131
P. R. China
Tel. +86 21 6093 0588
Fax +86 21 6093 0577

Esec (Shanghai)
Trading Co. Ltd.
1A0706, Singa Plaza Tower
8 Jin Ji Hu Road
Industrial Park
Suzhou 215021
P. R. China
Tel. +86 512 6767 1037
Fax +86 512 6767 1022

Esec (Shanghai)
Trading Co. Ltd.
Suite 801, Galaxy Center
Building
Caitian Road, Futian District
Shenzhen 518026
Guangdong Province
P. R. China
Tel. +86 755 8826 4058
Fax +86 755 8826 4067

Esec (Shanghai)
Trading Co. Ltd.
Suite 316, Building 2,
No. 8 KeXin Road
West Park of Chengdu
Hightech Zone
Chengdu 610731,
Sichuan Province
P. R. China
Tel. +86 28 879 581 59
Fax +86 28 879 581 59

Fico Tooling Leshan Co. Ltd.
High Tech Zone
Leshan 614012, Sichuan
P. R. China
Tel. +86 833 259 6385
Fax +86 833 259 6368

South Korea
Besi Korea Ltd.
#1204 Downtown Building
22-3 Sunae-dong
Bundang-gu, Sungnam-si,
Gyeonggi-do
Korea 463-825
Tel. +82 31 718 9002
Fax +82 31 718 9003

Taiwan
Besi Singapore Pte. Ltd.
Taiwan Branch
8F, 276 Minsheng Road
Hsinchu 30043
Taiwan
Tel. +886 3 515 3488
Fax +886 3 515 2253

Europe
Esec Ltd.
Hinterbergstrasse 32
6330 Cham
Switzerland
Tel. + 41 41 749 5111
Fax + 41 41 749 5440

Datacon Technology GmbH
Innstrasse 16
6240 Radfeld
Austria
Tel. +43 5337 6000
Fax +43 5337 600 66

Fico B.V.
Ratio 6
6921 RW Duiven
The Netherlands
Tel. +31 26 319 6100
Fax +31 26 319 6200

Meco Equipment
Engineers B.V.
Marconilaan 2
515 DR Drunen
The Netherlands
Tel. +31 416 384 384
Fax +31 416 384 300

Americas
Besi North America, Inc.
33 East Comstock Drive,
Suite 7
Chandler, AZ 85225
USA
Tel. +1 480 497 6404
Fax +1 480 497 9104

Online
sales@besi.com
www.besi.com

Datacon

8800 FC Quantum
The Reference in Flip Chip Bonding

Datacon

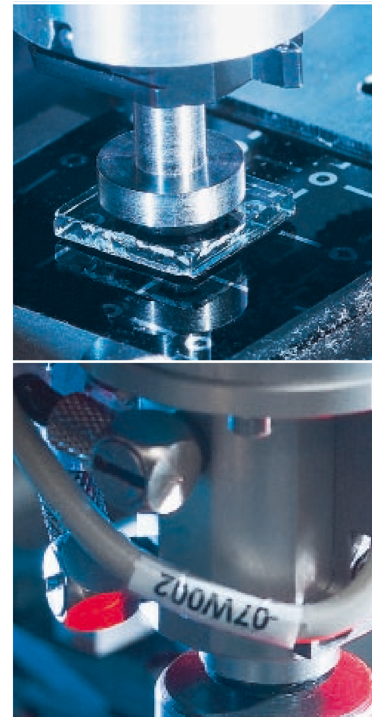
Capability and Flexibility
Innovation and flexibility … forward-looking concepts and strategies … a strong focus on the success of our customers – these are the keys to Datacon's leading position in the flip chip packaging market. The Datacon 8800 flip chip platform provides all features needed to cope with the challenges of today's flip chip production and the demands of tomorrow, while at the same time offering easy, hassle-free machine operation.

Flip Chip Challenges
For flip chip production highly reliable equipment is needed. Today's cutting edge packages often contain thousands of electrical interconnections. It takes only one of these interconnections to fail and the package to be rejected. Flip chip assembly equipment needs to provide stable and reliable production runs over extended periods of time to guarantee high yield and low cost. Datacon, as the leading vendor, has optimized its flip chip equipment since 1995 in cooperation with all leading customers and material suppliers to provide a vast variety of future-proof options – while still allowing swift, straightforward operation.

From time to time in this young technology, sudden 'technology shifts' of existing products from wire bonding to flip chip technology occur, driven by new developments and price changes in raw materials. In these cases, a machine is needed, which allows for a fast, error-free ramping of production volumes without any delays and risks. The Datacon 8800 platform is developed to handle such special challenges.

High-volume Flip Chip Production
The 8800 dedicated flip chip platform offers a solution for high-volume flip chip production combining high accuracy with high flexibility. With its dual bond head system, its accurate sub-systems and its enhanced fully automatic calibration, this machine supports all mainstream flip chip assembly processes.

Inside the 8800 FC Quantum, simultaneously working systems provide a remarkable performance of up to 10,000 UPH, while making no sacrifices regarding process stability and reliability. For operator-independent machine calibration a software-controlled fully automatic calibration routine is available.



Flip Chip Bonder 8800 FC Quantum
Capability and Flexibility for High-Volume Production

High Accuracy, High Speed – Unbeatable Cost-of-Ownership for Flip Chip
- Exceptional accuracy of ± 10µm @ 3 Sigma at highest speed
- High productivity, highest yield
- Operator-independent quality by fully automatic machine calibration

High Flexibility – No Compromise for any Production Process
- Capability to handle any flip chip size
- No restriction on substrate type (lead frames, strips, panels, wafers)
- Ready for ultra thin die handling

High Reliability – Consistent Quality, Minimal Risk
- Field-proven, reliable machine concept and production process
- Matching the requirements of IDMs and subcons (90% market share)
- Unbeatable benchmark for flip chip assembly equipment